

Fig. 2A

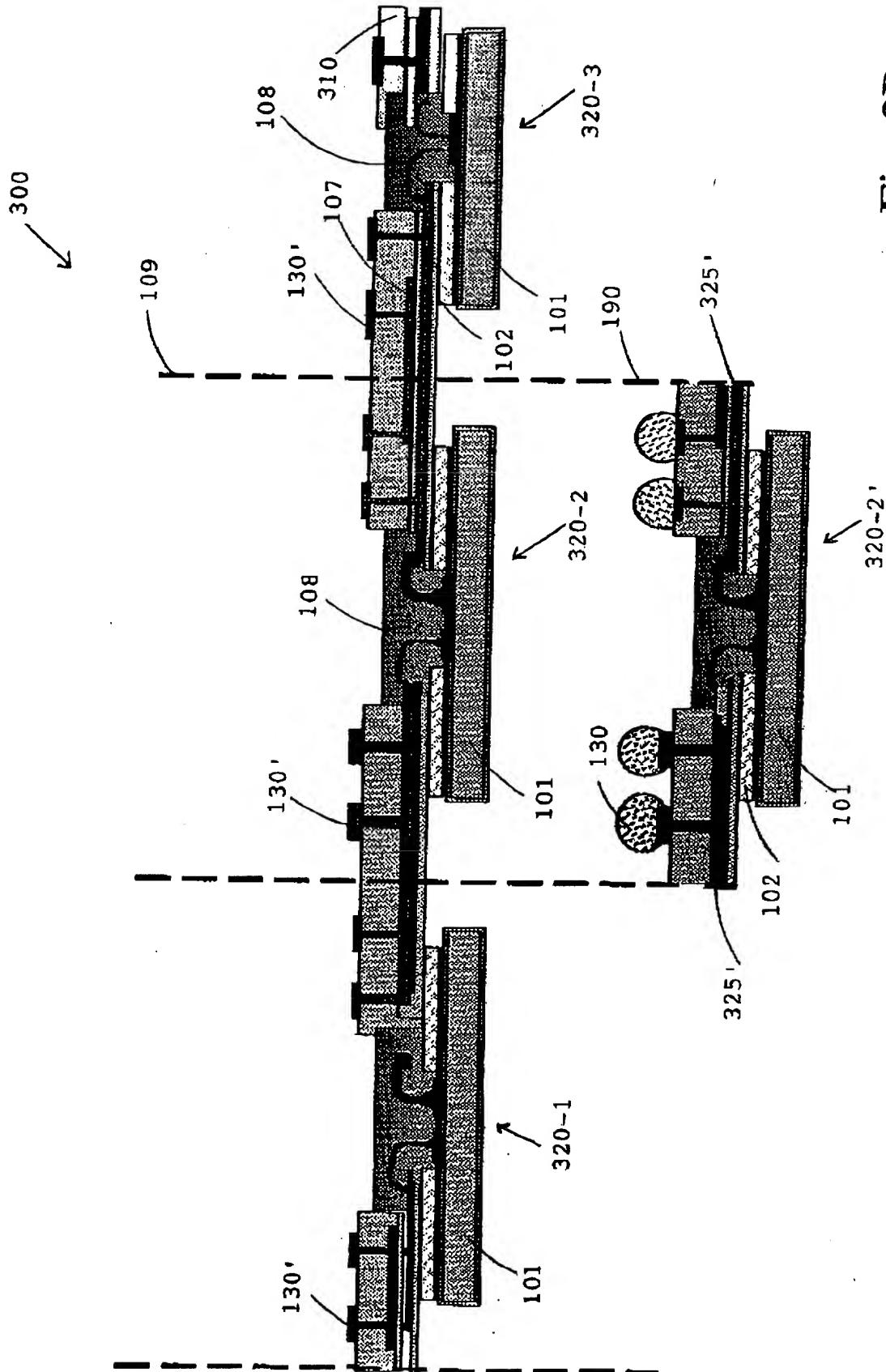


Fig. 2B

Fig. 2C

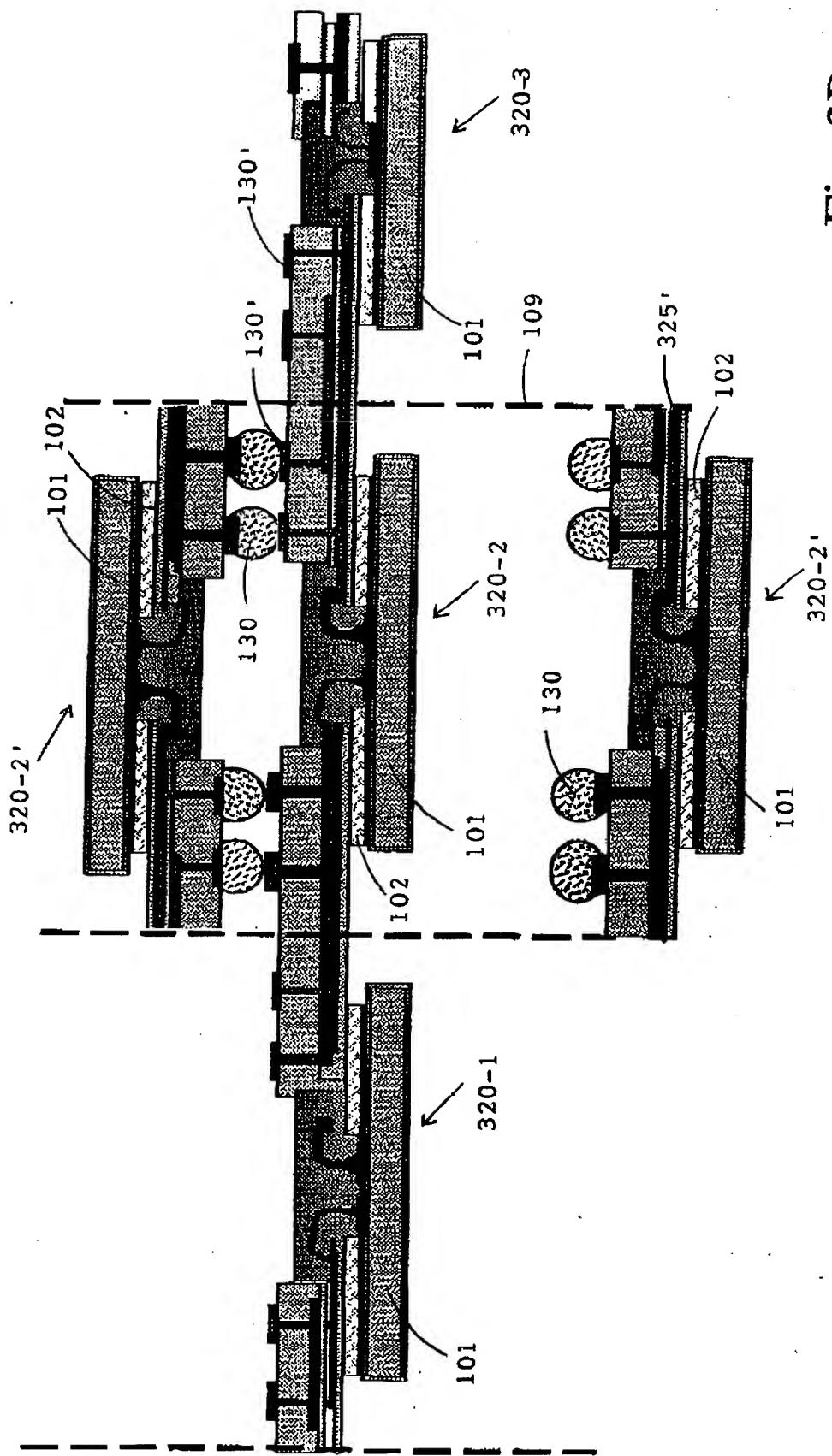


Fig. 2B

Fig. 5

VERY STRINGENT REQUIREMENTS FOR SMT PACKAGES

Package Qualification Tests with Level 3 Preconditioning

10 X Temperature Cycle (16 to +150 deg. C)

Bake at 125 deg. C for 24 Hrs

Temperature Humidity Soak (30 deg. C, 60% RH, 192 Hrs)

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Vapor Phase (215 deg. C, 60 Sec., 3 Passes)

<u>Thermal Shock Test</u>	<u>Temperature Cycle Test</u>	<u>Autoclave Test</u>	<u>Temp. Humidity Bias</u>
Liq. to Liq. -65 to +150 deg. C 1,000 Cycles	Air to Air -65 to +150 deg. C 1,000 Cycles	121 deg. C, 100% RH 15 PSIG, 96 Hrs.	85 deg. C, 85% RH 3.3 Volts, 1008 Hrs.

These requirements will not be applied on edge connected sub-system such as
SIMM/DIMM, PCMCIA or Slot 2 formats.